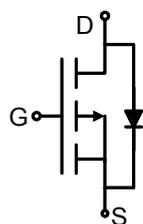
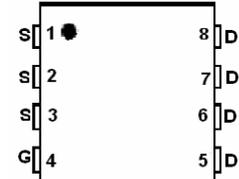


## P-Channel Enhancement Mode Power MOSFET

<p><b>DESCRIPTION</b></p> <p>The HT Ġ ÚĤÖ uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge and operation with gate voltages as low as 4.5V.</p> <p><b>GENERAL FEATURES</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS} = -30V, I_D = -25A</math>  <math>R_{DS(ON)} &lt; 35m\Omega @ V_{GS} = -4.5V</math>  <math>R_{DS(ON)} &lt; 20m\Omega @ V_{GS} = -10V</math></li> <li>● High Power and current handing capability</li> <li>● Lead free product is acquired</li> <li>● Surface Mount Package</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Battery Switch</li> <li>● Load switch</li> <li>● Power management</li> </ul>	 <p><b>Schematic diagram</b></p>  <p><b>Marking and pin assignment</b></p>
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### Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PT Ġ ÚĤÖ	PT Ġ ÚĤÖ	Á ÖĀ Í Ý Ī Š	Ø330mm	12mm	500 units

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	-25	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	-75	A
Maximum Power Dissipation	$P_D$	50	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	40	°C/W
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### Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	-33	-	V

Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.5	-3	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-10A$	-	15	20	$m\Omega$
		$V_{GS}=-4.5V, I_D=-7.0A$	-	21	35	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-15V, I_D=-9.1A$	10	-	-	S
<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=-15V, V_{GS}=0V,$ $F=1.0MHz$	-	1600	-	PF
Output Capacitance	$C_{OSS}$		-	350	-	PF
Reverse Transfer Capacitance	$C_{RSS}$		-	300	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, I_D=-1A,$ $V_{GS}=-10V, R_{GEN}=6\Omega$	-	10	-	nS
Turn-on Rise Time	$t_r$		-	15	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	110	-	nS
Turn-Off Fall Time	$t_f$		-	70	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-15V, I_D=-9.1A$ $V_{GS}=-10V$	-	30	-	nC
Gate-Source Charge	$Q_{gs}$		-	5.5	-	nC
Gate-Drain Charge	$Q_{gd}$		-	8	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-2.1A$	-	-	-1.2	V

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production





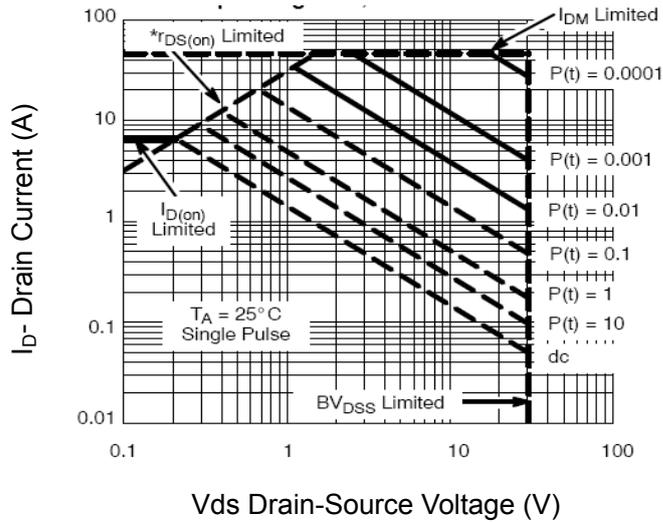


Figure 13 Safe Operation Area

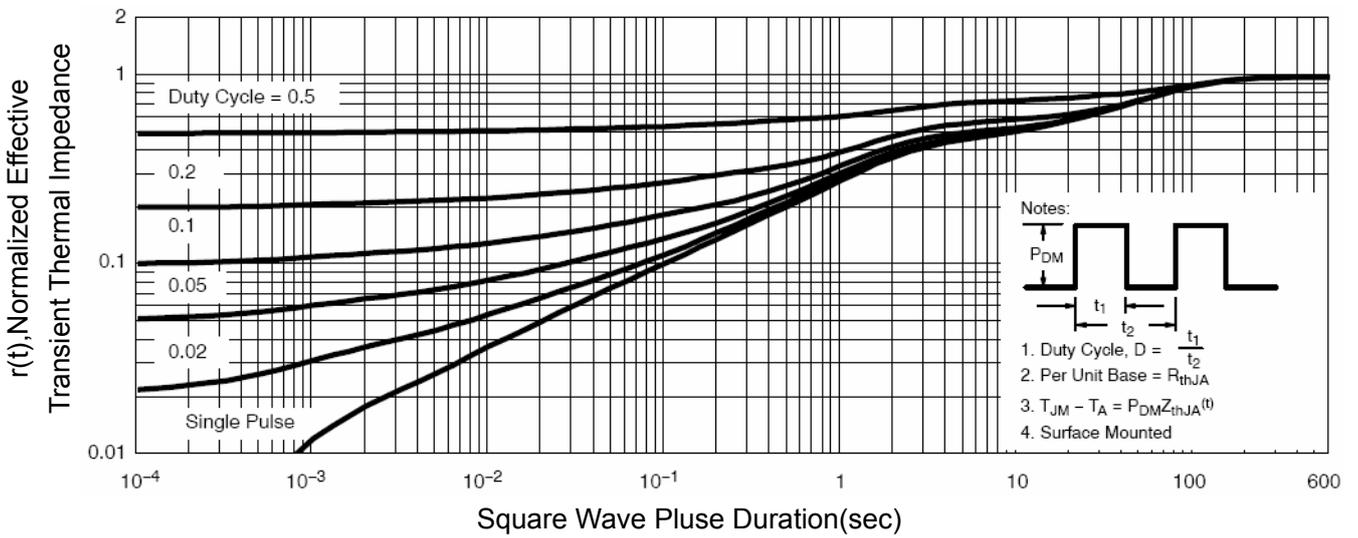
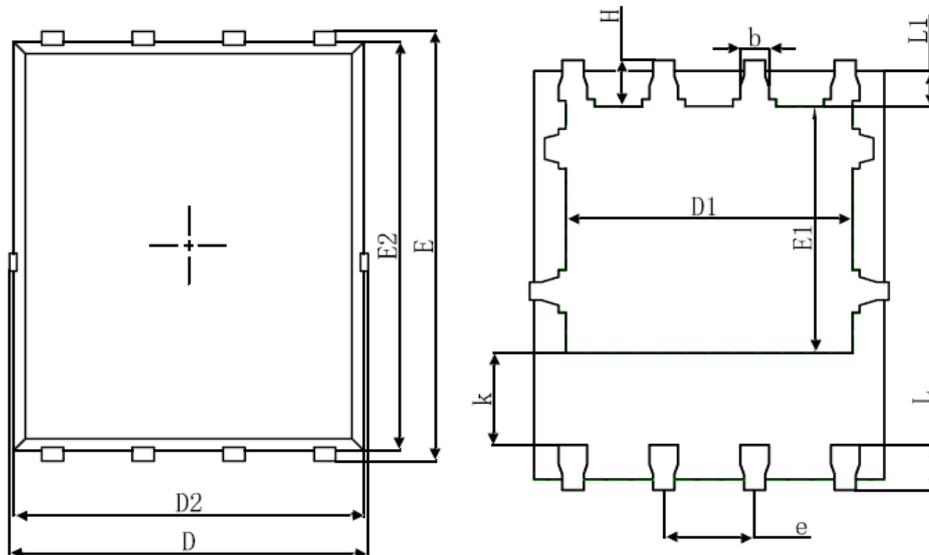


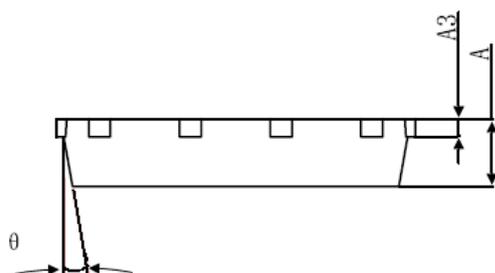
Figure 14 Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



Top View  
[顶视图]

Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°